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ABSTRACT

TORCH BUMP

A new method and sequence is provided for the creation of solder bumps. The design of the invention implements a torch bump, which is a solder bump comprising a base over which a solder bump is created. A first layer of dry film is laminated over a supporting surface over which first a layer of UBM has been deposited. A base for the solder bump is created in a first opening created through the first layer of dry film, the created base aligns with an underlying contact pad. A second dry film is laminated over the surface of the first dry film, a second opening is created through the second dry film that aligns with the created base of the solder bump. The opening through the second dry film is filled with solder by solder printing, the first and second layers of dry film are removed, the deposited layer of UBM is etched. Reflow is applied to the deposited solder, creating the torch solder bump (Fig. 9)